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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Josef Hoeglauer	06/27/2007
Ralf Otremba	06/21/2007
Xaver Schloegel	06/21/2007

RECEIVING PARTY DATA

Name:	Infineon Technologies AG	
Street Address:	StMartin-Str. 53	
City:	Munchen	
State/Country:	GERMANY	
Postal Code:	D-81669	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11736999

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ATTORNEY DOCKET NUMBER:	068758.0573

NAME OF SUBMITTER: Alfonso E. Juarez

Total Attachments: 3

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ATTORNEY DOCKET 068758.0573

PATENT APPLICATION 11/736,999

ASSIGNMENT

For good and valuable consideration, I, Jossef Hoeglauer, a citizen of Germany, residing at Aberlestr. 13A, 81371, München, Germany, Ralf Otremba, a citizen of Germany, residing at Ahornstr. 42, 87600 Kaufbeuren, Germany, and Xaver Schloegel, a citizen of Germany, residing at Raiffeisenstr. 22, 83679 Sachsenskam, Germany, hereinafter individually and collectively referred to as "Assignor";

Hereby sell, assign and transfer to Infineon Technologies AG, a corporation organized and existing under the laws of Germany, having its principal place of business at St.-Martin-Str. 53, D-81669 München, Germany, hereinafter "Assignee", its successors, assigns and legal representatives, the entire right, title and interest in and for the United States and all foreign countries, in and to any and all improvements which are disclosed in U.S. Patent application serial number 11/736,999 filed April 18, 2007, and entitled:

POWER SEMICONDUCTOR COMPONENT, POWER SEMICONDUCTOR DEVICE AS WELL AS METHODS FOR THEIR PRODUCTION

and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be filed in the United States and all foreign countries on said improvements;

Agree that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to but at the expense of said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and legal representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or legal representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

Covenant with said Assignee, it successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Full name of joint inventor

Inventor's Signature

Date

JOSEF HOEGLAUER

27-5, 2007

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AUS01:466228.1

PATENT REEL: 019507 FRAME: 0858 29-JUN-2007 16:34

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PATENT APPLICATION 11/736,999

ATTORNEY DOCKET 068758.0573

POWER SEMICONDUCTOR COMPONENT, POWER SEMICONDUCTOR DEVICE AS WELL AS METHODS FOR THEIR PRODUCTION

Full name of joint inventor

RALF OTREMBA

Inventor's Signature

Date 21.06, 201

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PATENT REEL: 019507 FRAME: 0859

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PATENT APPLICATION 11/736,999

ATTORNEY DOCKET 068758.0573

POWER SEMICONDUCTOR COMPONENT, POWER SEMICONDUCTOR DEVICE AS WELL AS METHODS FOR THEIR PRODUCTION

Full name of joint inventor

Inventor's Signature

Date

XAVERSCHLOEGEL

21.06.07

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AUS01:466228.1

RECORDED: 07/02/2007

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